

COLD MOUNTING CONSUMABLES



cold mounting resin



curing agent

Code	Description	Package
MLP-CM1	<ol style="list-style-type: none"> 1. cold mounting compound, fast speed/good transparency/low viscosity/high strength 2. for metal processing without heating, pressure and mounting press 3. curing time: 25°C, 25min 4. usage: cold mounting resin 3:curing agent 2 	<ol style="list-style-type: none"> 1. cold mounting resin 1000g 2. curing agent 800ml 3. Ø30mm cold mounting mold 1 pc 4. plastic cup 20 pcs 5. stirring rod 40 pcs, spoon 1 pc
MLP-CM2	<ol style="list-style-type: none"> 1. epoxy resin, low viscosity, good permeability, completely transparent 2. for samples which can not be heated or mounting pressed, like PCB, SMT and other micro-slice samples 3. curing time: 25°C, 5~6h 4. usage: resin liquid 2:curing agent 1 	<ol style="list-style-type: none"> 1. resin liquid 1000ml 2. curing agent 500ml 3. Ø30mm cold mounting mold 1 pc 4. plastic cup 20 pcs 5. stirring rod 40 pcs
MLP-CM3	<ol style="list-style-type: none"> 1. fast epoxy, fast curing products, completely transparent 2. for samples which can not be heated or mounting pressed, like PCB, SMT and other micro-slice samples 3. curing time: 25°C, 1h 4. usage: resin liquid 2:curing agent 1 	<ol style="list-style-type: none"> 1. resin liquid 1000ml 2. curing agent 500ml 3. Ø30mm cold mounting mold 1 pc 4. plastic cup 20 pcs 5. stirring rod 40 pcs
MLP-CM4	<ol style="list-style-type: none"> 1. low viscosity epoxy, good permeability, completely transparent 2. for samples which can not be heated or mounting pressed, like PCB, SMT and other micro-slice samples 3. curing time: 25°C, 3~4h 4. usage: resin liquid 2:curing agent 1 	<ol style="list-style-type: none"> 1. resin liquid 1000ml 2. curing agent 500ml 3. Ø30mm cold mounting mold 1 pc 4. plastic cup 20 pcs 5. stirring rod 40 pcs
MLP-CM5	<ol style="list-style-type: none"> 1. low heat release epoxy, small, shrink, completely transparent 2. for samples which can not be heated or mounting pressed, like PCB, SMT and other micro-slice samples 3. curing time: 25°C, 20~24h 4. usage: resin liquid 3:curing agent 1 	<ol style="list-style-type: none"> 1. resin liquid 1000ml, 2. curing agent 300ml 3. Ø30mm cold mounting mold 1 pc 4. plastic cup 20 pcs, 5. stirring rod 40 pcs
MLP-CM6	<ol style="list-style-type: none"> 1. cold mounting compound, fast speed/ceramics white/low viscosity/high strength 2. for metal processing without heating, pressure and mounting press 3. curing time: 25°C, 25min 4. usage: cold mounting resin 3:curing agent 2 	<ol style="list-style-type: none"> 1. cold mounting resin 1000g 2. curing agent 800ml 3. Ø30mm cold mounting mold 1 pc 4. plastic cup 20 pcs 5. stirring rod 40 pcs, spoon 1 pc